

In the claims

1. (currently amended) A method for fabricating a transistor comprising:
 - forming a gate electrode on a semiconductor substrate;
 - forming a first preliminary source/drain region and a pocket junction region through a first ion implantation process using the gate electrode as a mask, the pocket junction region being formed under the first preliminary source/drain region;
 - forming a first oxide layer ~~with uniform thickness~~ on the substrate including the gate electrode;
 - forming a nitride layer ~~with uniform thickness~~ on the first oxide layer;
 - forming a second oxide layer over the nitride layer;
 - forming spacers on sidewalls of the gate electrode;
 - forming a second preliminary source/drain region through a second ion implantation process using the spacers as a mask;
 - removing the nitride layer and the first oxide layer on the surface of the substrate; and
 - diffusing substantially all of the implanted ions in a horizontal direction of the substrate by performing a thermal treatment process for the resulting substrate.
2. (original) The method as defined by claim 1, further comprising performing a thermal treatment process prior to the removal of the nitride layer and the first oxide layer.